

Product Change Notification - KSRA-03AYHE005

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Date:

07 May 2018

Product Category:

8-bit PIC Microcontrollers; Capacitive Touch Sensors

Affected CPNs:**Notification subject:**

CCB 3296 Initial PCN: Qualification of gold (Au) bond wire as secondary wire material for selected Atmel products available in 44L TQFP (10x10x1.0mm) package at MTAI Assembly site

Notification text:**PCN Status:**

Initial notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of gold (Au) bond wire as secondary wire material for selected Atmel products available in 44L TQFP (10x10x1.0mm) package at MTAI Assembly site

Pre Change:

Using palladium coated copper wire with gold flash (CuPdAu) bond wire

Post Change:

Using palladium coated copper wire with gold flash (CuPdAu) or gold (Au) bond wire

Pre and Post Change Summary:

	Pre Change	Post Change	
Assembly Site	Microchip Technology Thailand (HQ) / MTAI	Microchip Technology Thailand (HQ) / MTAI	Microchip Technology Thailand (HQ) / MTAI
Wire material	CuPdAu	CuPdAu	Au
Die attach material	3280	3280	3280
Molding compound material	G700HA	G700HA	G700HA
Lead frame material	C7025	C7025	C7025

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve on-time delivery performance by qualifying gold (Au) bond wire for selected Atmel devices at MTAI assembly site.

Change Implementation Status:

In Progress

Estimated Qualification Completion Date:

May 2018

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	May2018				
Workweek	18	19	20	21	22
Initial PCN Issue Date		X			
Qual Report Availability					

Final PCN Issue Date					X
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Method to Identify Change:

Traceability code

Qualification Plan:

Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History:

May 07, 2018: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

[PCN_KSRA-03AYHE005_Qual_Plan.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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